



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LED DISPLAY**LTS-5825CKR-P**
DATA SHEET

<u>ITEM</u>	<u>Description</u>	<u>By</u>	<u>DATE</u>
1	New Spec	Lester Chen	2011/03/18

FEATURES

- * 0.56 inch (14.22 mm) DIGIT HEIGHT
- * CONTINUOUS UNIFORM SEGMENTS
- * LOW POWER REQUIREMENT
- * EXCELLENT CHARACTERS APPEARANCE
- * HIGH BRIGHTNESS & HIGH CONTRAST
- * WIDE VIEWING ANGLE
- * SOLID STATE RELIABILITY
- * CATEGORIZED FOR LUMINOUS INTENSITY

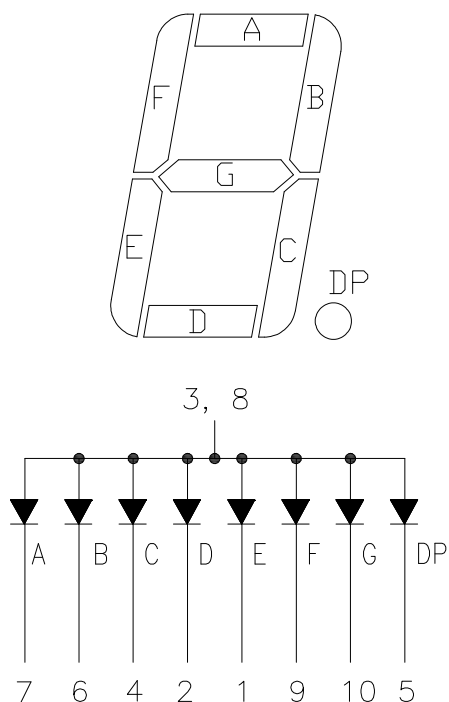
DESCRIPTION

The LTS-5825CKR-P is a 0.56 inch (14.22 mm) digit height single digit SMD display. This device utilizes AllnGaP SUPER RED LED chips which are made from AllnGaP on a non-transparent GaAs substrate. The display has gray face and white segments.

DEVICE

PART NO.	DESCRIPTION
AllnGaP SUPER RED	Common Anode
LTS-5825CKR-P	

INTERNAL CIRCUIT DIAGRAM



PIN CONNECTION

No.	CONNECTION
1	CATHODE E
2	CATHODE D
3	COMMON ANODE
4	CATHODE C
5	CATHODE DP
6	CATHODE B
7	CATHODE A
8	COMMON ANODE
9	CATHODE F
10	CATHODE G

ABSOLUTE MAXIMUM RATING AT Ta = 25 ° C

PARAMETER	MAXIMUM RATING	UNIT
Power Dissipation Per Segment	70	mW
Peak Forward Current Per Segment (Frequency 1Khz,10% duty cycle)	90	mA
Continuous Forward Current Per Segment	25	mA
Forward Current Derating from 25 ° C	0.28	mA/° C
Operating Temperature Range	-35 ° C to +105 ° C	
Storage Temperature Range	-35 ° C to +105 ° C	
Soldering Conditions: 1/16 inch Below Seating Plane for 3 Seconds at 260 ° C		

ELECTRICAL / OPTICAL CHARACTERISTICS AT Ta = 25 ° C

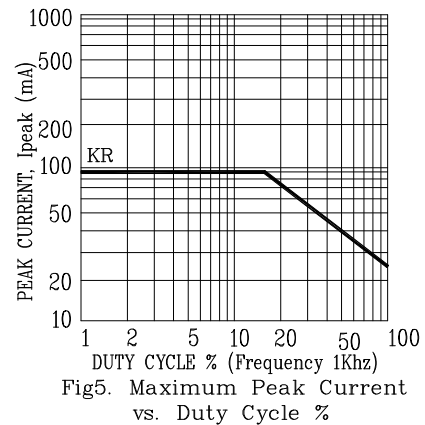
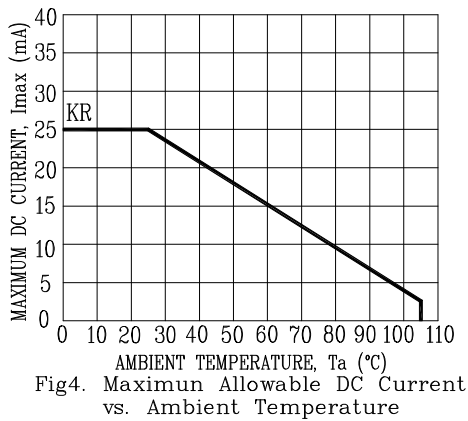
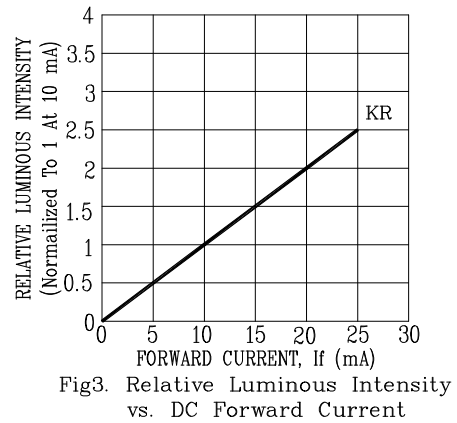
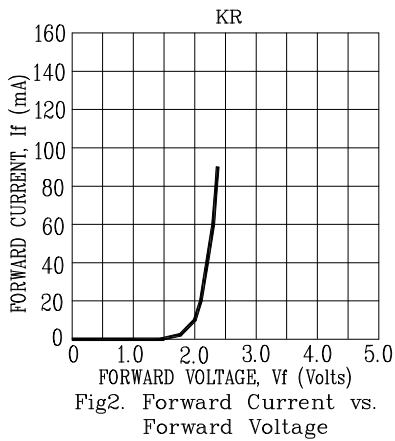
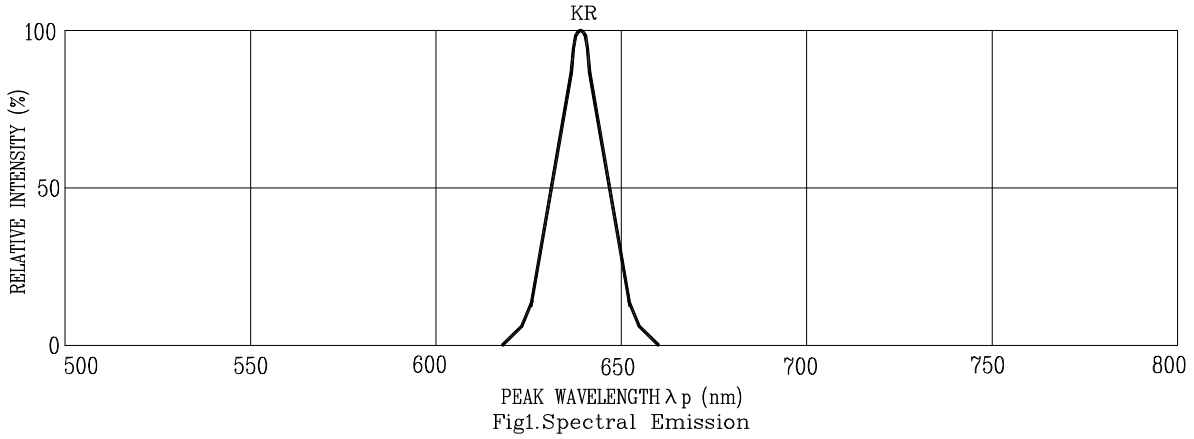
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Luminous Intensity	IV		T.B.D		mcd	If=20mA
Peak Emission Wavelength	λ_p		639		nm	If=20mA
Spectral Line Half-Width	$\Delta\lambda$		20		nm	If=20mA
Dominant Wavelength	λ_d		631		nm	If=20mA
Forward Voltage Per Segment	V _F		2.0	2.6	V	If=20mA
Reverse Current Per Segment ⁽²⁾	I _R			100	uA	V _R =5V
Luminous Intensity Matching Ratio	Iv-m			2:1		If=2mA

Note:

- Luminous intensity is measured with a light sensor and filter combination that approximates the CIE (Commision Internationale De L'Eclairage) eye-response curve.
- Reverse voltage is only for IR test. It can not continue to operate at this situation.

TYPICAL ELECTRICAL / OPTICAL CHARACTERISTIC CURVES

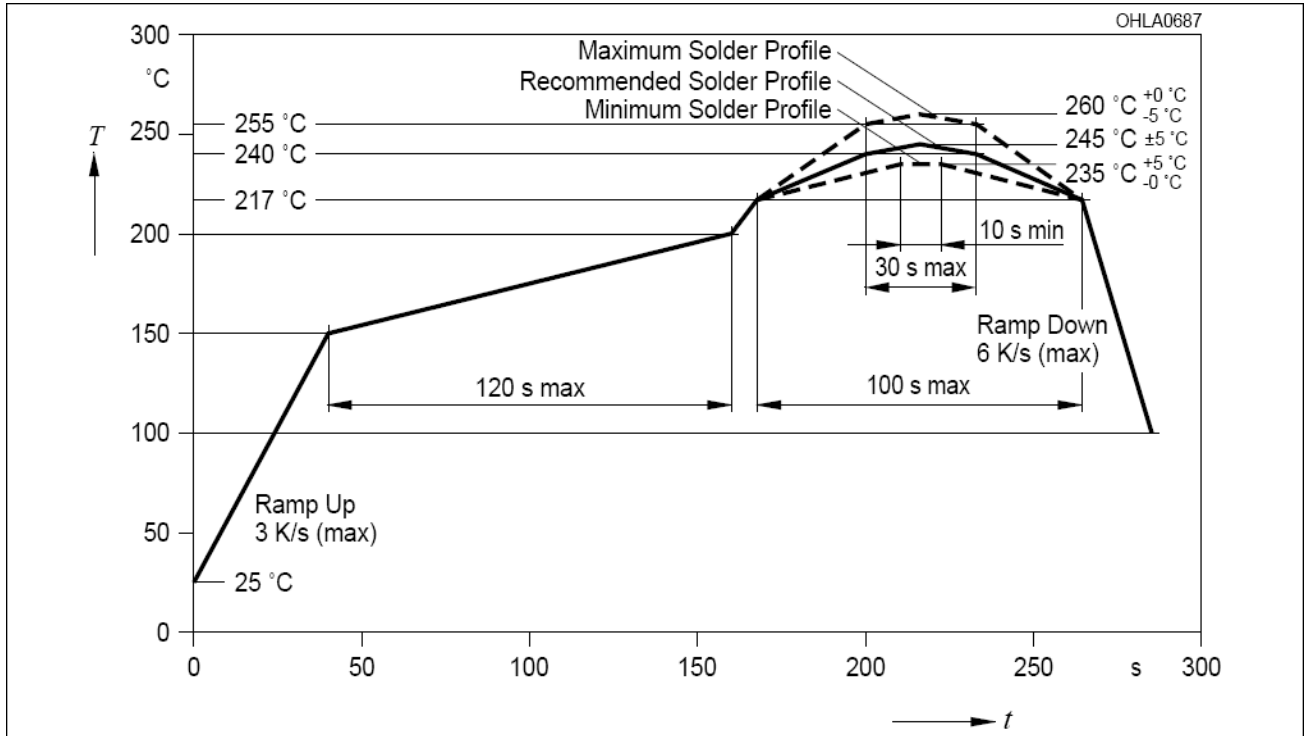
(25°C Ambient Temperature Unless Otherwise Noted)



NOTE : KR=AlInGaP SUPER RED

SMT SOLDERING INSTRUCTION

(Number of reflow process shall be less than 2 times, and cooling process to normal temperature is required between the first and the second soldering process)

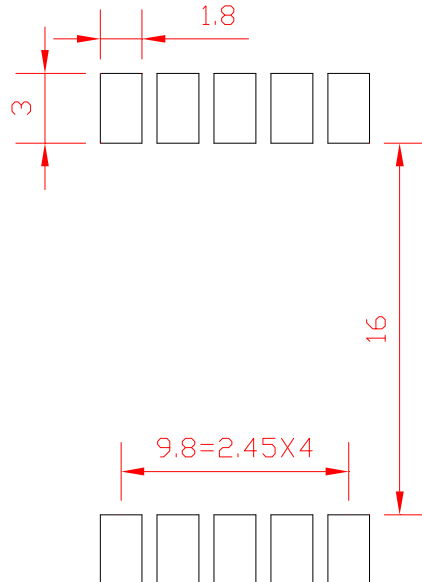


Note:

1. Recommended soldering condition:

Reflow Soldering (Two times only)		Soldering Iron (One time only)	
Pre-heat:	120~150°C.	Temperature	300°C Max.
Pre-heat time:	120sec. Max.	Soldering time	3sec. Max.
Peak temperature:	260°C Max.		
Soldering time:	5sec. Max.		

2. Number of reflow process shall be less than 2 times, and cooling process to normal temperature is required between the first and the second soldering process.

RECOMMENDED SOLDERING PATTERN (UNIT: MM)**PACKING REEL DIMENSIONS**

T.B.D.

PACKING CARRIER DIMENSIONS

1. Taping parts:

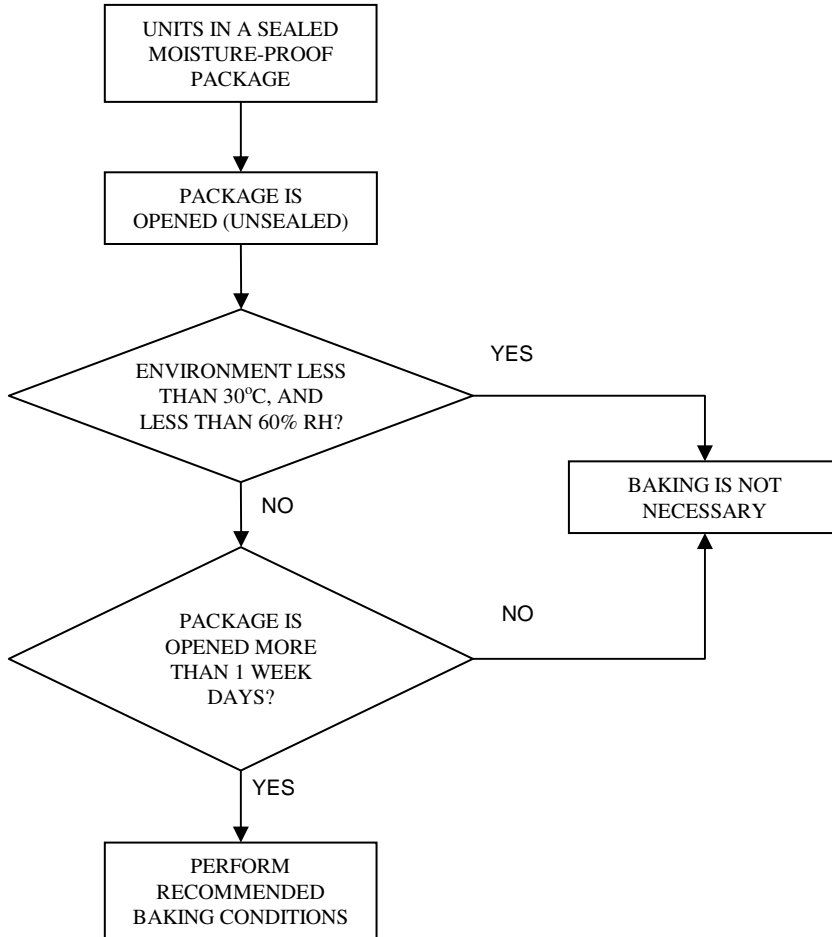
T.B.D.

2. Trailer part/ Leader part:

T.B.D.

MOISTURE PROOF PACKAGING

All N/D SMD displays are shipped in moisture proof package. The displays should be stored at 30°C or less and 90% RH or less. Once the package opened, moisture absorption begins.



Baking Conditions

If the parts are not stored in dry conditions, they must be baked before reflow to prevent damage to the parts.

Package	Temperature	Time
In Reel	60°C	≥ 48hours
In Bulk	100°C	≥ 4hours
	125°C	≥ 2hours

Baking should only be done once.